

### Product Change Notification / LIAL-06WFCQ261

## Date:

03-Feb-2022

# **Product Category:**

8-bit Microcontrollers

# PCN Type:

Manufacturing Change

## **Notification Subject:**

CCB 3405.001 Final Notice: Qualification of G700LA mold compound material for selected Atmel ATMEGA168PB, ATMEGA88PB, ATMEGA48PB, ATMEGA808 and ATMEGA1608 device families available in 32L TQFP (7x7x1mm) package assembled at ASCL assembly site.

## Affected CPNs:

LIAL-06WFCQ261\_Affected\_CPN\_02032022.pdf LIAL-06WFCQ261\_Affected\_CPN\_02032022.csv

# Notification Text:

**PCN Status:** Final Notification

PCN Type:Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of G700LA mold compound material for selected Atmel ATMEGA168PB, ATMEGA88PB, ATMEGA48PB, ATMEGA808 and ATMEGA1608 device families available in 32L TQFP (7x7x1mm) package assembled at ASCL assembly site.

### Pre and Post Change Summary:

	Pre Cl	hange	Post Change		
Assembly Site	ASE Group Chung-Li (ASCL)		ASE Group Chung-Li (ASCL)		
Wire Material	Cu	PdCu	Cu	PdCu	
Die Attach Material	EN-4900GC		EN-4900GC		
Molding Compound Material	CEL-9240HF10AK		G700LA		
Lead-Frame Material	EFTEC64		EFTEC64		

### Impacts to Data Sheet:None

### Change ImpactNone

**Reason for Change:**To improve on-time delivery performance by qualifying G700LA mold compound material.

#### Change Implementation Status: In Progress

Estimated First Ship Date: February 17, 2022 (date code: 2208)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

### Time Table Summary:

	February 2022					
Workweek	0 6	0 7	0 8	0 9	1 0	
Qual Report Availability	x	/	0	9	0	
Final PCN Issue Date	Х					
Estimated Implementation Date			х			

Method to Identify Change:Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**February 03, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

### Attachments:

#### PCN\_LIAL-06WFCQ261\_Qual Report 1of2.pdf PCN\_LIAL-06WFCQ261\_Qual Report 2of2.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. LIAL-06WFCQ261 - CCB 3405.001 Final Notice: Qualification of G700LA mold compound material for selected Atmel ATMEGA168PB, ATMEGA88PB, ATMEGA48PB, ATMEGA808 and ATMEGA1608 device families available in 32L TQFP (7x7x1mm) package assembled at ASCL assembly site.

Affected Catalog Part Numbers (CPN)

ATMEGA168PB-AU ATMEGA168PB-AN ATMEGA168PB-ANR ATMEGA168PB-AUR ATMEGA88PB-AU ATMEGA48PB-AU ATMEGA88PB-AN ATMEGA48PB-AN ATMEGA88PB-ANR ATMEGA48PB-ANR ATMEGA88PB-AUR ATMEGA48PB-AUR ATMEGA808-AF ATMEGA1608-AF ATMEGA1608-AU ATMEGA808-AU ATMEGA1608-AUR ATMEGA808-AUR ATMEGA1608-AFR ATMEGA808-AFR